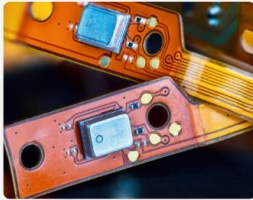
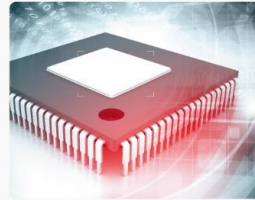


SNAP CURE ANISOTROPIC CONDUCTIVE PASTE



ELECTRONICS

Conductive for
RFID
Display
Connection



SEMICONDUCTOR

Die Attach for
Wire-Bond Based
Flip-Chip Based

FEATURES



Snap Cure 30s, 180dC

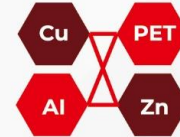
Protect Fragile Material
High Throughput

**Curing profile varies based on device design*



Conductive or No, Up to You

Pure Adhesion w / o Press
Conductive w / Press



Heterogeneous Interfaces

Bonding for different interface material
Cu / Al / Zn / PET

PROPERTY

Product	Snap Cure ACP
Color	Yellowish Silver Grey
Vis. @10rpm (cp)	20,000
Thixotropic Index	2.3
Tg (dC)	105



CONTACT

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OUR STRENGTH



25%
Ph. D.

Professional R&D
10+ Years Experience



Customization
Capability



Agile
Responsiveness